



Final Product Change Notification

201801006F01U01

Issue Date: 18-Feb-2018

Effective Date: 19-May-2018

UPDATE

Here's your personalized quality information concerning products Digi-Key purchased from NXP. For detailed information we invite you to view this notification online



QUALITY

Change Category

☐ Wafer Fab Process

☐ Assembly Process

☐ Product Marking

☐ Test Location

☐ Design

☐ Wafer Fab Materials

☒ Assembly Materials

☐ Mechanical Specification

☐ Test Process

☐ Errata

☐ Wafer Fab Location

☒ Assembly Location

☐ Packing/Shipping/Labeling Equipment

☐ Test

☐ Electrical spec./Test coverage

MC9S12VR 48/32LQFP
Assembly Site Expansion
from ATTJ (NXP, Tianjin,
China) to ASE (Chung Li,
Taiwan)

Details of this Change

NXP Semiconductors is announcing the assembly site expansion for MC9S12VR 48/32LQFP from the current NXP-ATTJ, Tianjin China assembly facility to ASE, Chung Li, Taiwan (ASE-CL) assembly facility.

The wire type and wire diameter will be identical between the two assembly sites.

NXP-ATTJ is qualified with epoxy SUMITOMO DA SUMITOMO CRM-1064MB-L, mold compound Hitachi CEL9240HF16FL.

ASE-CL has been qualified with epoxy Hitachi EN-4900G, mold compound SUMITOMO EME-G631HA.

The lead frame dimensions will have difference visually under X-ray with no change in base and plating material. No change to package case outline.

The wafer thickness will change from NXP-ATTJ 0.28mm to ASE-CL 0.33mm.

These changes correspond to the ZVEI Delta Qualification Matrix ID: SEM-PW-03, SEM-PA-03, SEM-PA-07, SEM-PA-11 and SEM-PA-18.

Why do we Implement this Change

Qualification of ASE-CL to ensure manufacturing flexibility and customer supply assurance.

Identification of Affected Products

The assembly site, among other information, is reflected in the package trace code.

Please refer to the marking comparisons file in the attachment.

Product Availability

Sample Information

Samples are available from 28-Feb-2018

Qualified samples part numbers

KC667350CLCR/KC667343CLCR/KC667350VLFR/KC667343CLFR/KC667350VLCR/KC667313CLCR/K9S12VR64AF0AMLC/K9S12VR64AF0AMLF from ASE-CL material will be provided upon request.

Production

Planned first shipment 31-May-2018

Update Information

1.Updated Qualified samples part numbers

1).Removed K9S12VR48AF0MLC.

2).Added K9S12VR64AF0AMLC and K9S12VR64AF0AMLF.

2.Changed Supplier Name from Freescale semiconductor to NXP semiconductor in CofDC.

3.Added a new affected part number S9S12VR64AF0MLCR in the products list.

4. Updated Details of this Change

1).Added "The wafer thickness will change from NXP-ATTJ 0.28mm to ASE-CL 0.33mm".

2).Added ZVEI Delta Qualification Matrix ID:SEM-PW-03.

Impact

no impact to the product's functionality anticipated.

Disposition of Old Products

NXP will reserve the right to ship from any location based on market demand situation.

Timing and Logistics

Your acknowledgement of this change, conform JEDEC JESD46 D, is expected till 20-Mar-2018.

Contact and Support

For all inquiries regarding the ePCN tool application or access issues, please contact NXP "Global Quality Support Team".

For all Quality Notification content inquiries, please contact your local NXP Sales Support team.

For specific questions on this notice or the products affected please contact our specialist directly:

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Position Product Engineer

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Customer Focus, Passion to Win.

NXP Quality Management Team.

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Affected Part Number

S9S12VR64AF0MLF